

XENSIV™ smart sensors showcase: Key portfolio highlights

2026 May

confidential

Infineon at a glance

Growth areas



Energy
green and efficient

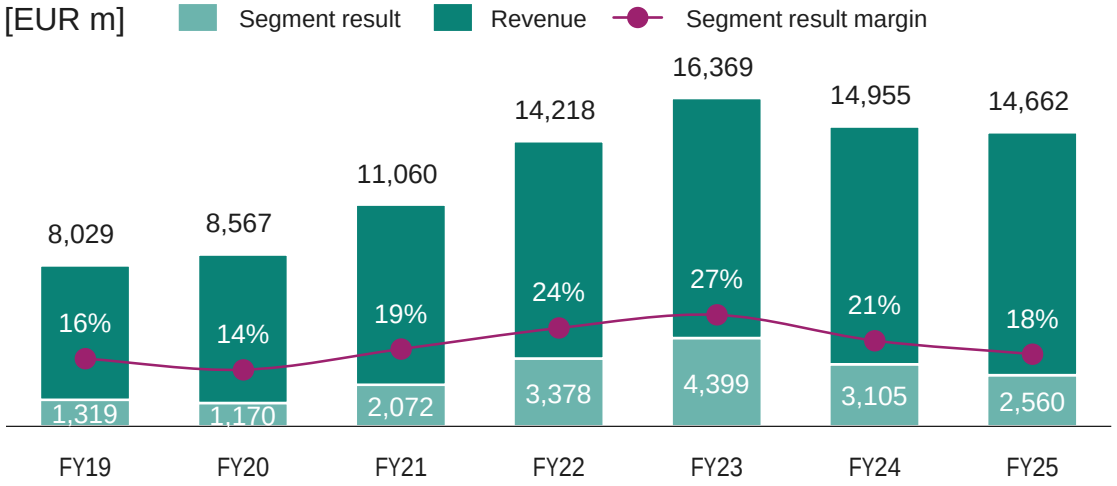


Mobility
clean and safe

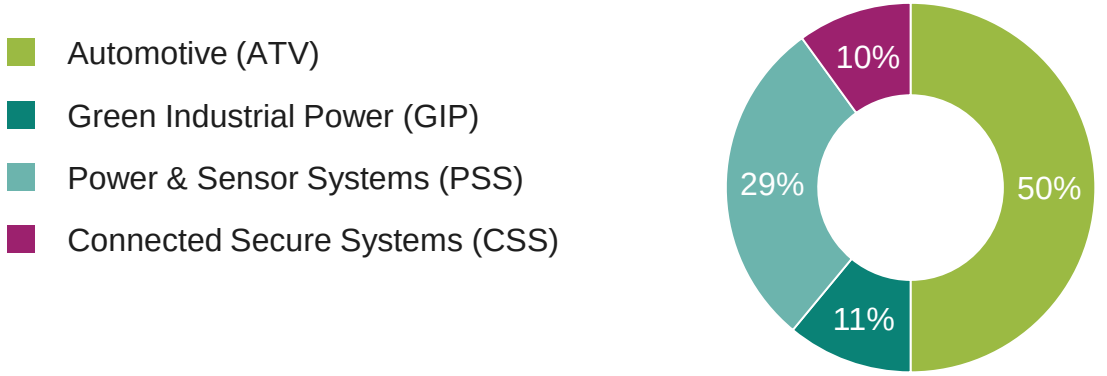


IoT
smart and secure

Financials



FY25 revenue by segment[1]

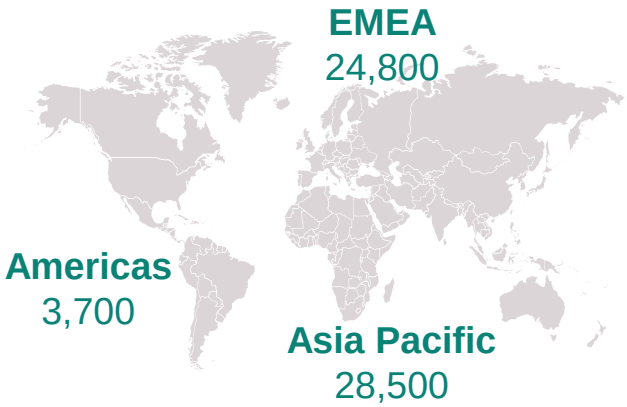


Employees[1]

57,000
employees worldwide

75
R&D and

14
manufacturing locations[2]



For further information: Infineon Annual Report.
1 2025 Fiscal year (as of 30 September 2025) | **2** As of 30 September 2025

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Infineon offering system solutions combining our best-in-class XENSIV™ sensors with compute capability, connectivity and software

We sense what matters and provide full system solutions



Sense
accurately & reliably

- XENSIV™ PAS CO2 sensor
- XENSIV™ radar sensor
- REAL3™ 3D image sensor (ToF)
- XENSIV™ pressure sensor
- XENSIV™ MEMS microphones
- XENSIV™ magnetic sensor
- XENSIV™ current sensor

Compute
raw data to extract information

- PSOC™ 4
- PSOC™ 6
- CAPSENSE™ embedded in PSOC™
- XMC™

Connect securely
to the cloud

- AIROC™ Wi-Fi®
- AIROC ™ Wi-Fi® + Bluetooth®
- BT only & BT (BLE) in µC
- BLE & 802.15.4 SoC Matter over Thread
- OPTIGA™ Trust Hardware Security

Software
suite in ModusToolbox™

Sensor **use case algorithm** and **example codes** for rapid IoT development

Power
the device

From MOSFETs, ICs, Switches and many more in LV, MV and H.



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Infineon SURF serves all markets with a broad sensor portfolio to provide best solutions in Auto, Industrial and Consumer



Automotive



Industrial



Consumer

Magnetic Sensors			MEMS				Radar		RF	
Speed	Current	Position	Pressure	Gas	Sound	Inno MEMS	Auto	Consumer	Mobile & Wireless IF	Protection
Wheel speed Trans-mission speed Engine speed	Internal rail External rail	3D, Angle, Linear Inductive Switches	Auto, Phone Barometric Airbag, Manifold, Tire pressure	Air quality, Leakage CO_2 H_2 Propane	SiMic in e.g. Phones, Head-sets, Auto	Laser beam scanner (LBS) Ultra-sound (CMUT*)	Radar 24GHz 60GHz 77GHz 3D optical Time-of-Flight		RF Comm LNA Active Antennas Wireless Infrastructure	ESD Passives

Closely aligned with capacitive sensing ICs, Infineon‘s µC and connectivity portfolio (WiFi/BLE)

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XENSIV™ MEMS microphones

Infineon is market leader for MEMS microphone technology



Market leader
in MEMS microphone market
In 2023 with market share
SiMic dies **>** 47%*

Top 3
MEMS sensor player
Next to Bosch and STM

Leading player
In providing solutions for many different applications such as Smartphones, Hearables & Headphones, Laptops & Tablets, Smart Home & Speakers, Cameras, Smart Watches, Hearing Aids, AR/VR

Innovation leader
We manufacture the industries highest SNR microphones, while lowering power consumption and package size

2.3 bn
MEMS sold in 2024

300+ employees
directly involved in
Silicon mic biz (w/o manufacturing)

100+ mn
Packaged mics sold in 2024

* Source: Omdia MEMS Microphone Report 2024

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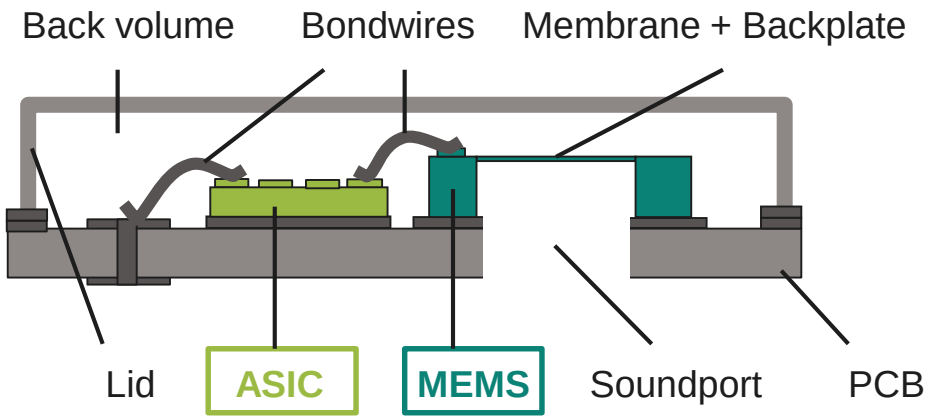
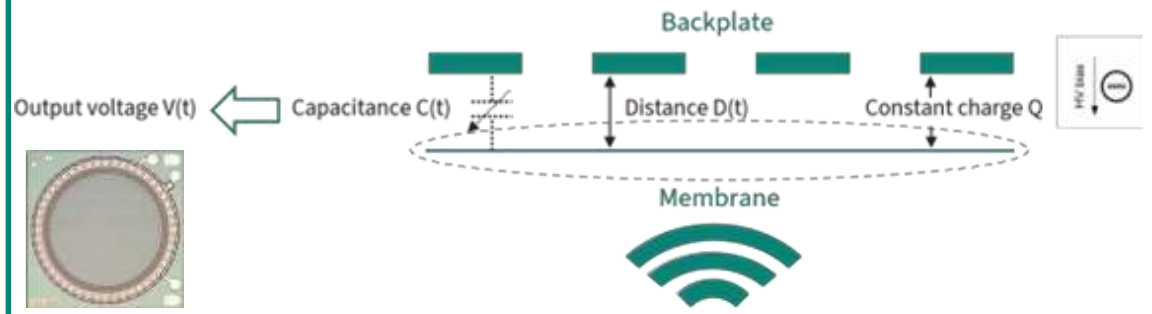
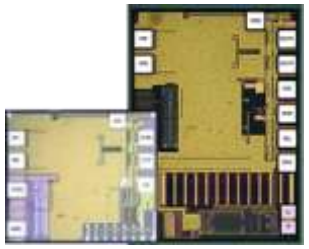
Infineon has a full ownership of every building block of XENSIV™ MEMS microphones bringing unprecedented innovation & quality



Advanced acoustic sensor

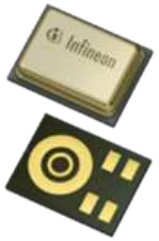


ASIC



- Integral part of the microphone
- Receives the output of the MEMS
- Amplifies the output of the MEMS
- Provides the correct bias voltage

Package



- Provides proper acoustical working environment
- Provides mechanical and environmental protection
- Shields against EMI and RF interference

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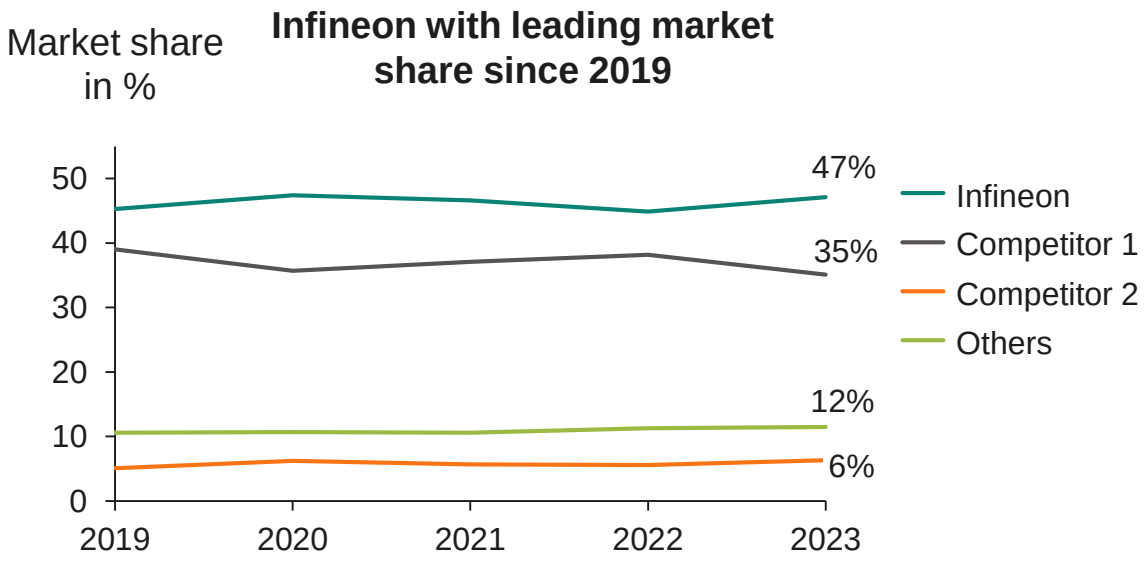
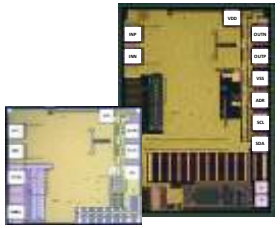
Infineon maintains market leadership for MEMS microphones for 5th year in a row and is strongly growing in own packaged business

Microphone bare die market share 2019-2023*





MEMS



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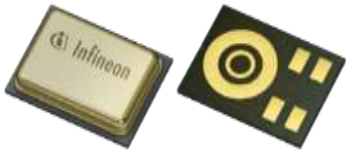

Package

* Source: Omdia MEMS Microphone Report 2024

Strong growth for Infineon packaged microphones

- >10 packaged mics with highest performance
- Further growth in both mid range and high-end market
- Next generation of >5 SBP products to launch in 2025



Bare die business via packaging houses

- High volume commodity projects
- Enabling dual sourcing for OEMs

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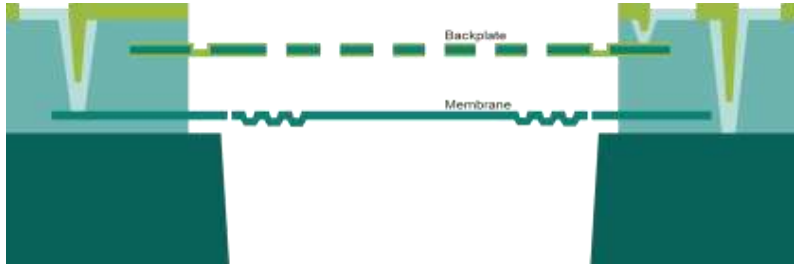
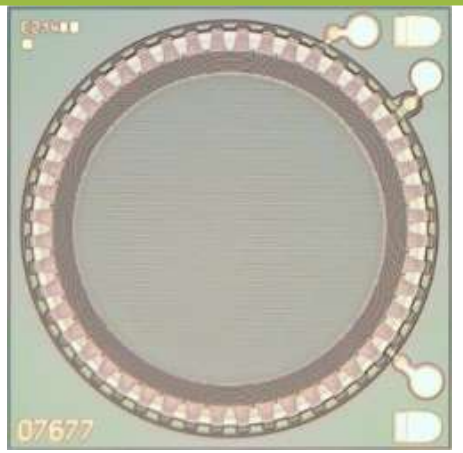
Infineon is offering two different MEMS designs: Sealed Dual Membrane (SDM) & Single Backplate (SBP)

MEMS

Single Backplate (SBP)



- Industry standard
- Best SNR for small packages
- Simple and robust against water & dust - IP57 for all digital Infineon microphones

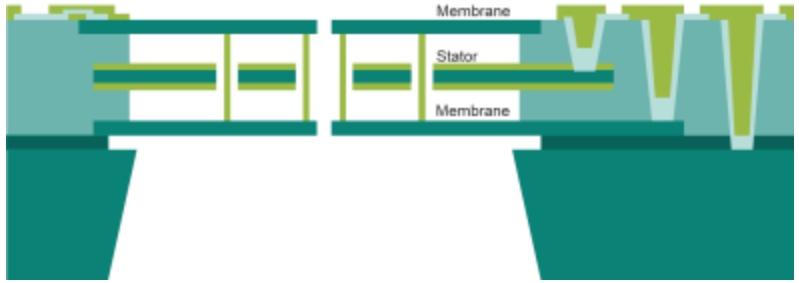


1.45 mm * 1.45 mm

Chip dimension

0.8 mm * 0.8 mm

Sealed Dual Membrane (SDM)



- Infineon proprietary technology
- Highest acoustic performance benchmark
- Best fit medium & large packages
- IP57 reduces need for water proof mesh



1.7 mm * 1.7 mm

Chip dimension

1.45 mm * 1.45 mm

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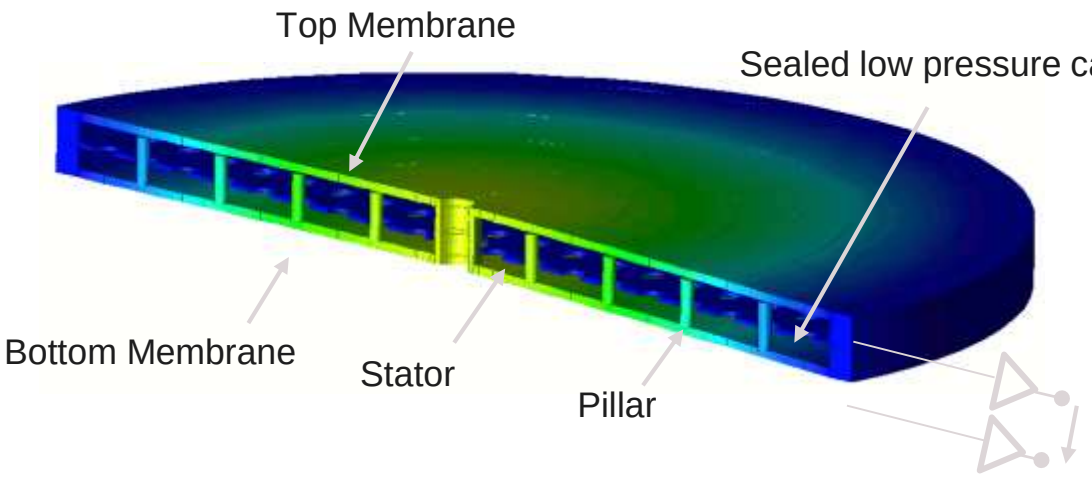
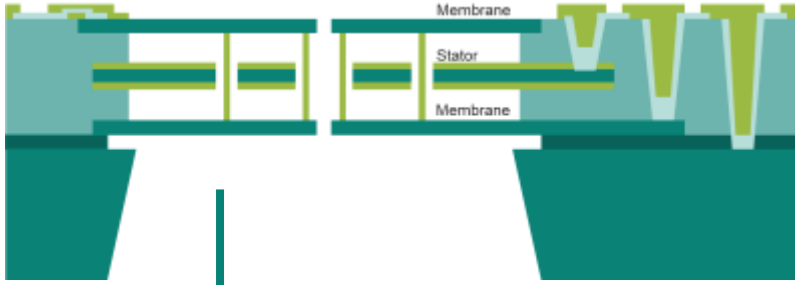
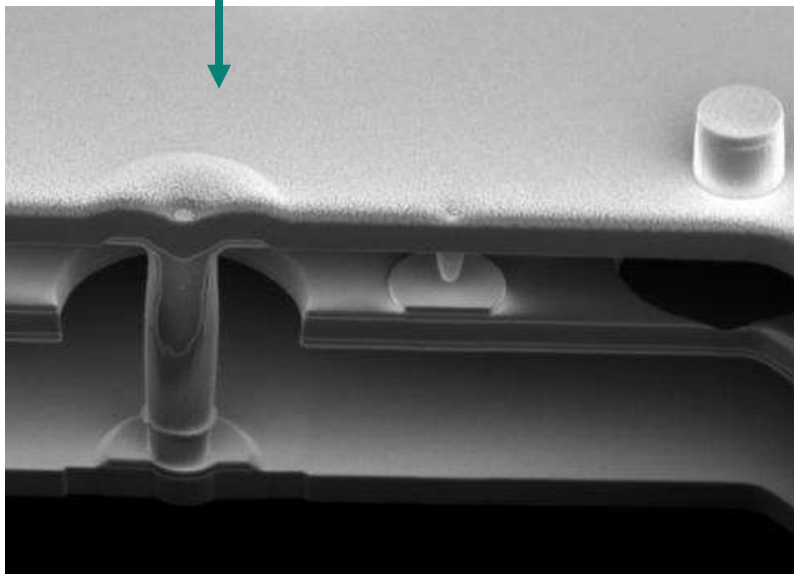
Our Sealed Dual Membrane (SDM) technology enables up to 80 dB SNR

Sealed Dual Membrane (SDM) – Revolutionary technology for capacitive MEMS microphones







- True-differential topology
  - Enables ultra high SNR of up to 76 dB SNR (82 dB for dual MEMS)
  - Distortion improvement by cancellation of even order distortion
- IP57 environmental robustness leads to less field returns and better manufacturability

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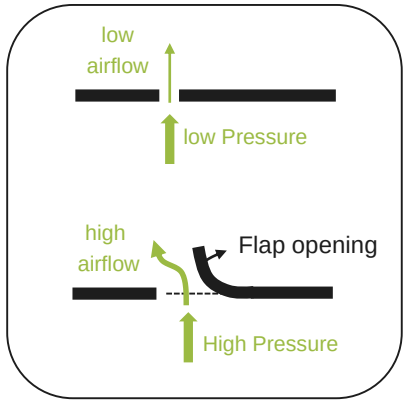
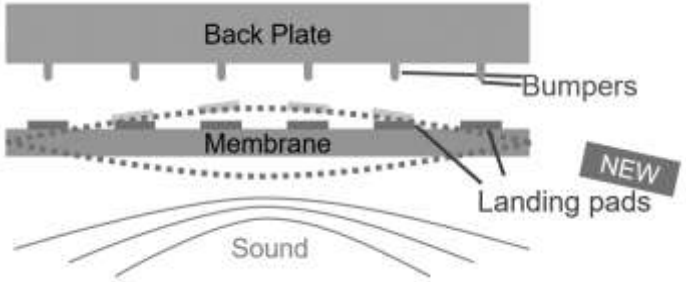
Our Single Backplate (SBP) MEMS offer improved robustness combined with a performance of up to 69 dB SNR

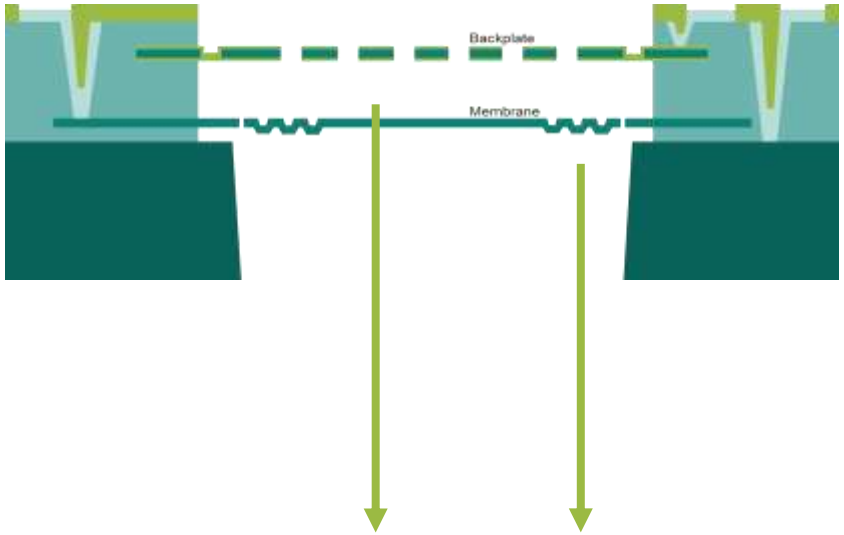
Single Backplate (SBP) – New generation with improved robustness

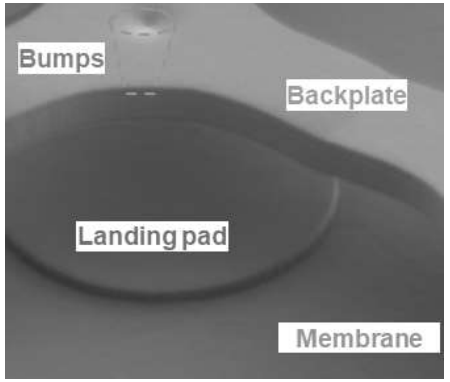
- **„Flaps“** is a unique IFX protected IP used in all Infineon SBP microphones:
  - In acoustical regime (<170 dB), flaps are closed: Membrane seals air gap towards sound port, acoustic ventilation is provided by ~1µm flap slits
  - At extreme pressure events (~1 bar), flaps are open: Pressure across membrane is equalized



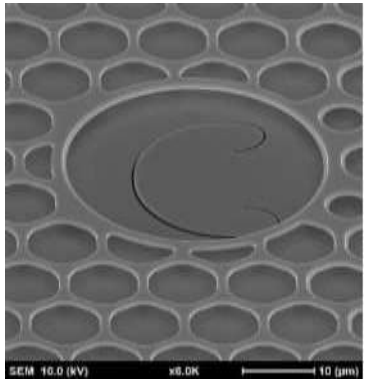
- **Landing pads** on membrane increase the mechanical robustness in the new generation of Infineon SBP microphones:
  - Landing pads below bumps protects membrane from destruction by high frequent swinging during air blow test







Landing Pads


Flaps

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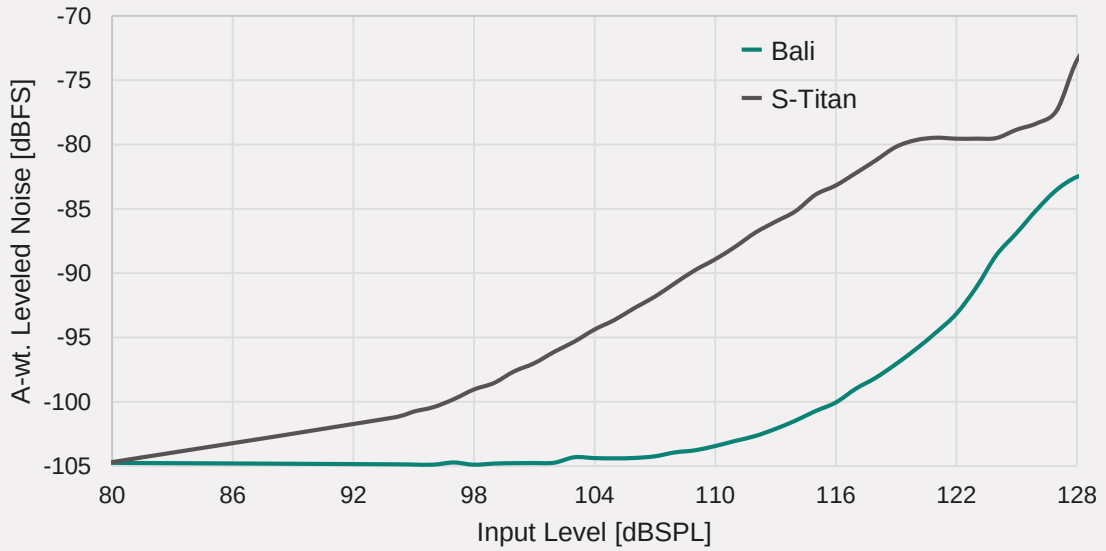
Infineon's chipset demonstrates superior performance in aspects beyond the typical acoustic parameters

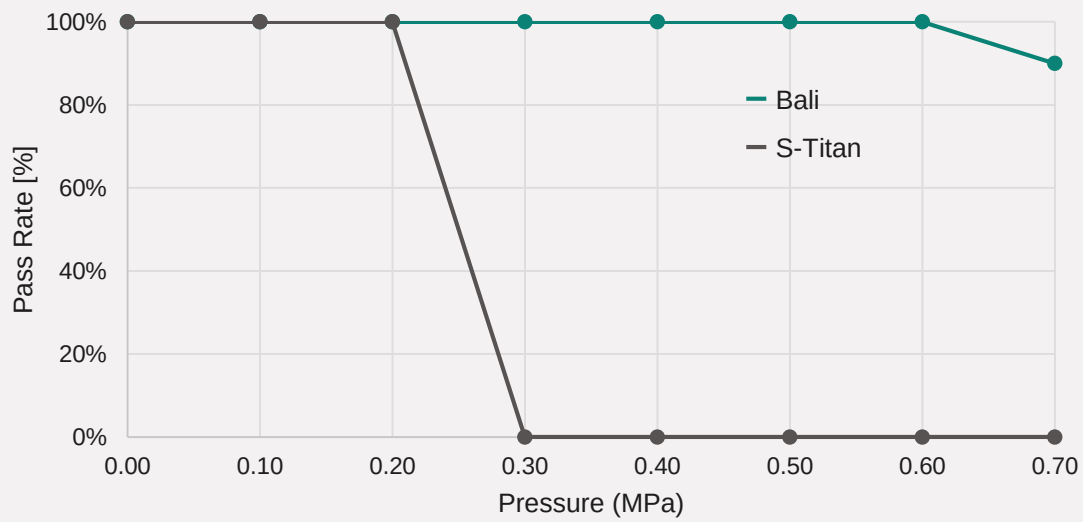
Leveled noise



Why this is important?

- The SNR represents the device's noise performance under controlled laboratory conditions.
- Leveled noise is the device noise performance in the presence of a signal, reflecting a real-world usage scenario
- Leveled noise is a crucial factor to consider when evaluation audio zoom and noise-cancellation algorithms

Air bust Robustness



Why this is important?

- Airburst robustness contribute to the overall durability of electronic devices
- Higher air burst robustness protects the device against sudden and intense pressure events
- Infineon MEMS provide superior air bust robustness over K-Titan

* S-Titan samples available in open market

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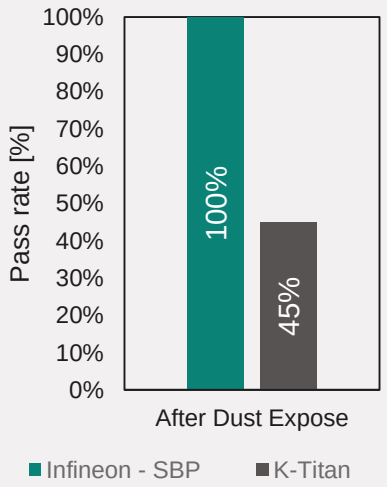
Infineon's chipset demonstrates superior performance in aspects beyond the typical acoustic parameters

IP5x Particle robustness

- IP5x specifies the resistance against dust



- **Test Specification**:
  - Talc dust according to IEC 60529
- **Pass specification**:
  - Sensitivity: ± 3dB
  - SNR: ± 3dB
  - LFRO: ± 3 Hz



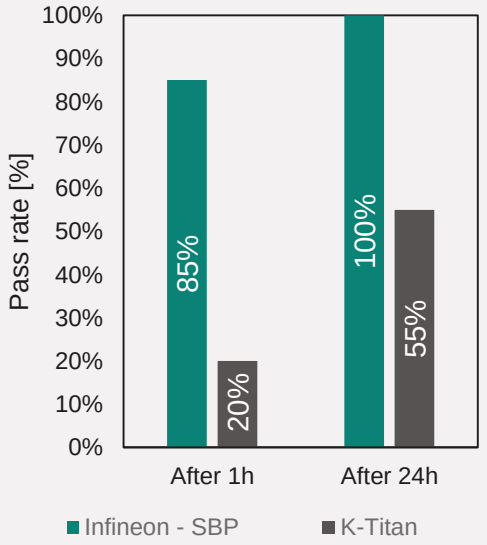
IP5x rating reduces particle-related defects, boosting module assembly yield.

IPx4 Water resistant

- IPx4 rating measures water splash resistance



- **Test Specification**:
  - Flow rate: 10L/min
  - Distance: 300 mm
  - Total Duration: 5 minutes
  - Angle max: 40° on each side
- **Pass specification**:
  - Sensitivity: ± 3dB
  - SNR: ± 3dB
  - LFRO: ± 3 Hz





* K-Titan samples available in open market

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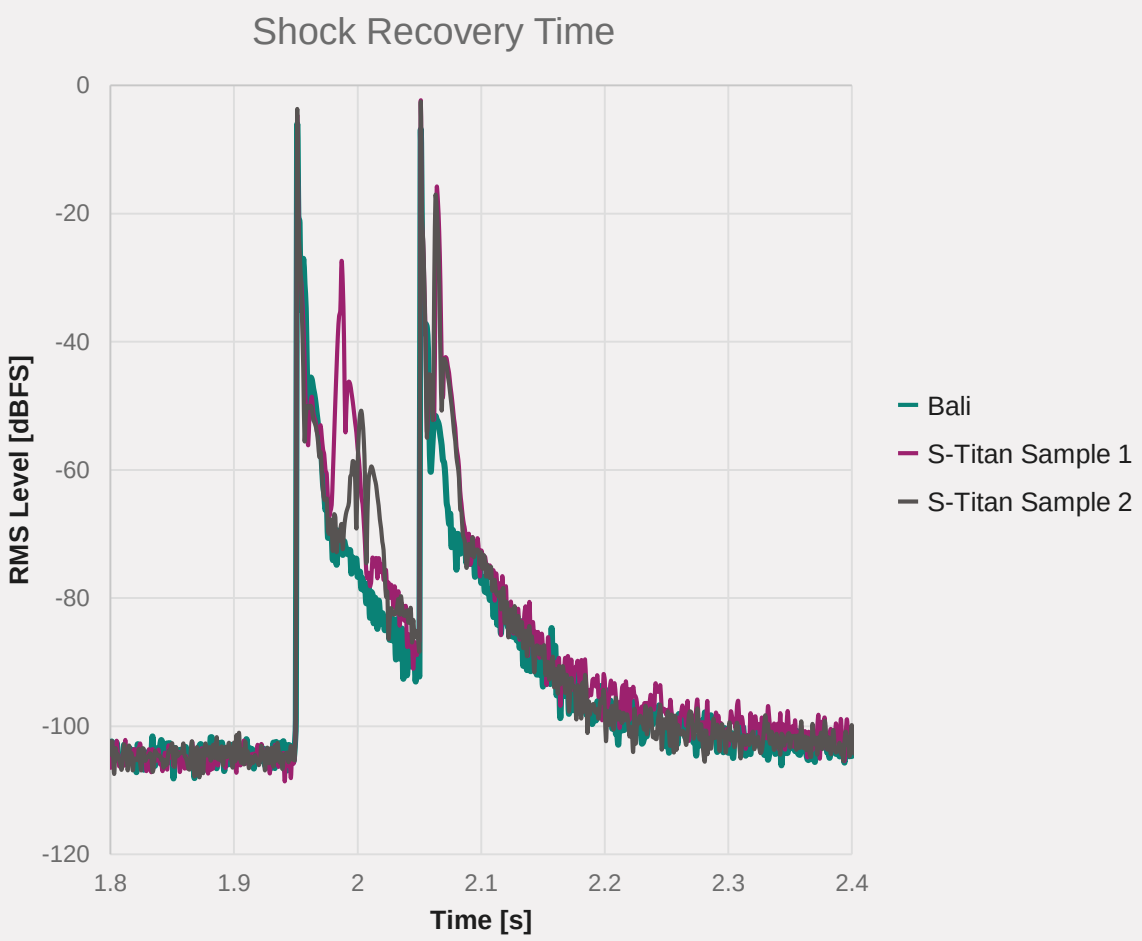
Infineon's chipset demonstrates superior performance in aspects beyond the typical acoustic parameters

Shock recovery time



Why this is important?

- After a high dBSPL event (higher than AOP) where microphone clips, it is desirable to go back to normal operation as soon as possible
- To model this, an impulse waveform with high sound pressure level is applied and microphone noise is measured
- The Infineon MEMS microphone noise returns to normal while the competitor S-Titan mic shows nonlinear behavior

* S-Titan samples available in open market

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MEMS Microphone trend for AI

High SNR and Sensitivity is key for microphones

Sound pressure halves with double the distance

- Relevant indicator: sound pressure halves with double the distance, leaving less signal input
- Sound channel, room conditions, and system design cause further signal losses

Example:

IM73A135 XENSIV™ MEMS microphone with ultra-high dynamic range

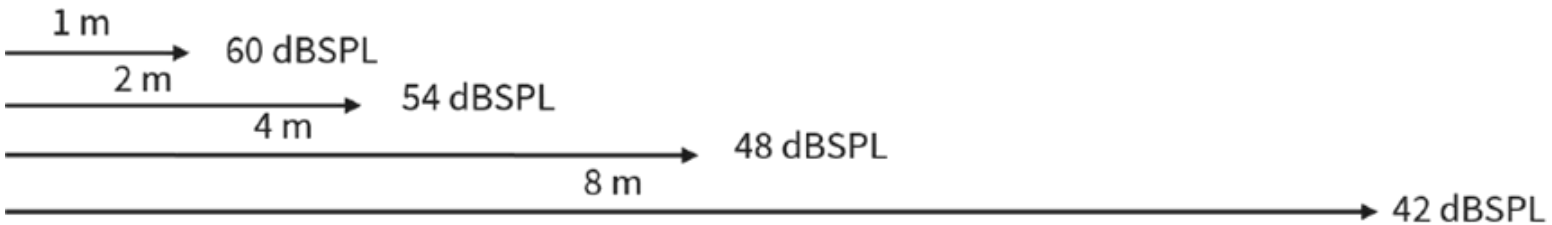
SEN: sensitivity

Ratio of the analog output voltage/digital output value to the sound pressure level of the incoming sound wave

SNR: signal to noise ratio

Referenced to 94 dBSPL; indicates the noise floor level and the quietest sounds that can be captured





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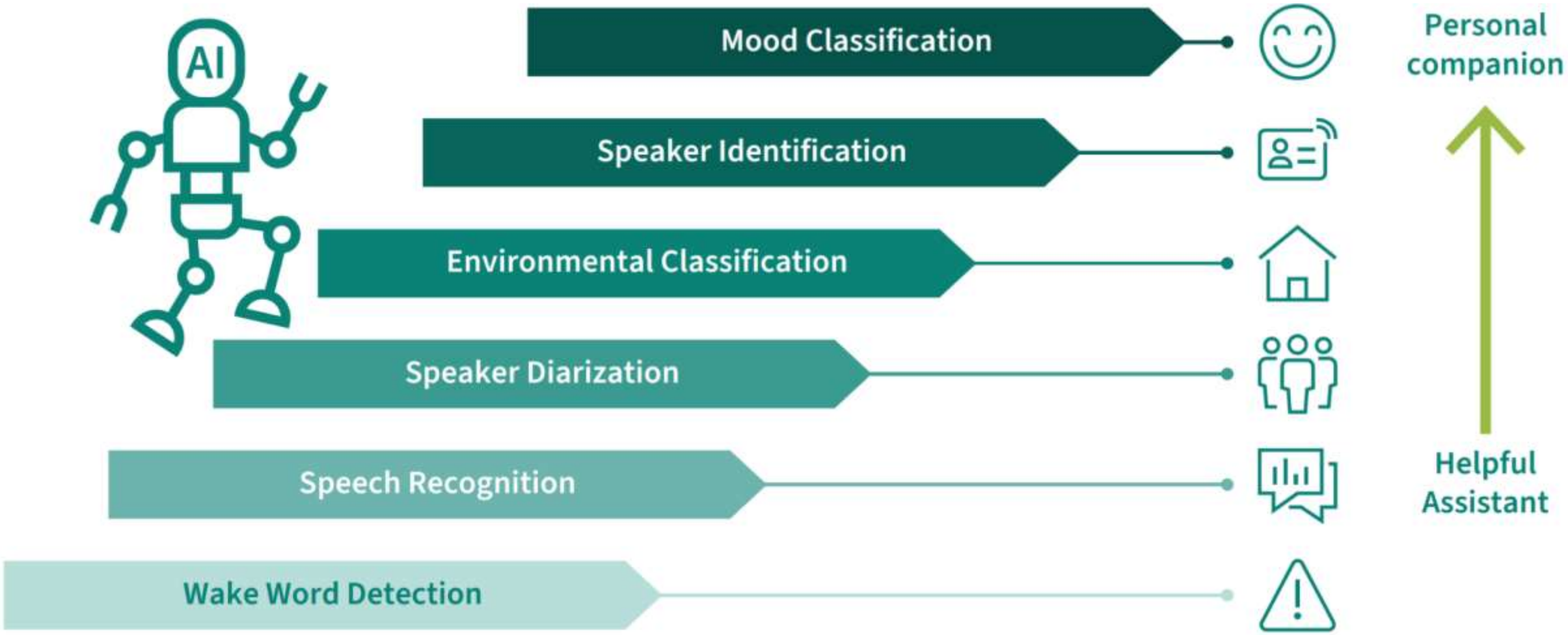
What is the role of voice in the emerging AI ecosystem?



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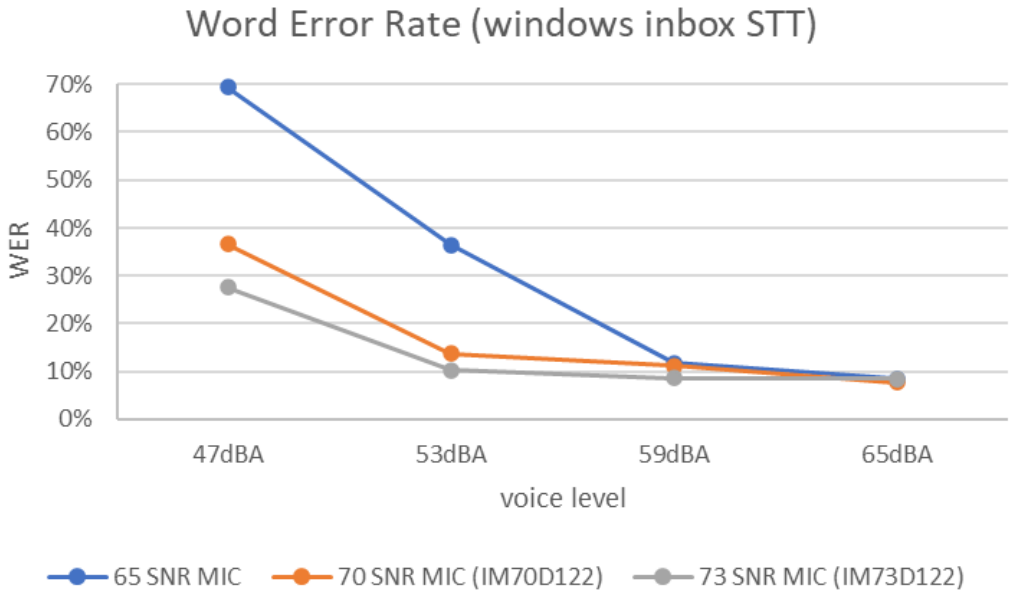
High-SNR microphones show a considerable advantage on the Word Error Rate in comparison to mid-end performance microphones

Word Error Rate (WER) in Quite			
Mouth level (dBA) / Equivalent distance (m)	Microphone SNR 65dBA	IM70D122 SNR 70dBA	IM73D122 SNR 73dBA
47 dBA / 2.8m	69.40%	36.63%	27.53%
53 dBA / 1.4m	36.46%	13.71%	10.24%
59 dBA / 0.7m	11.72%	11.09%	8.65%
65 dBA / 0.35m	8.42%	7.68%	8.48%





Wake-up word detection



Voice command



Speech to text transcription

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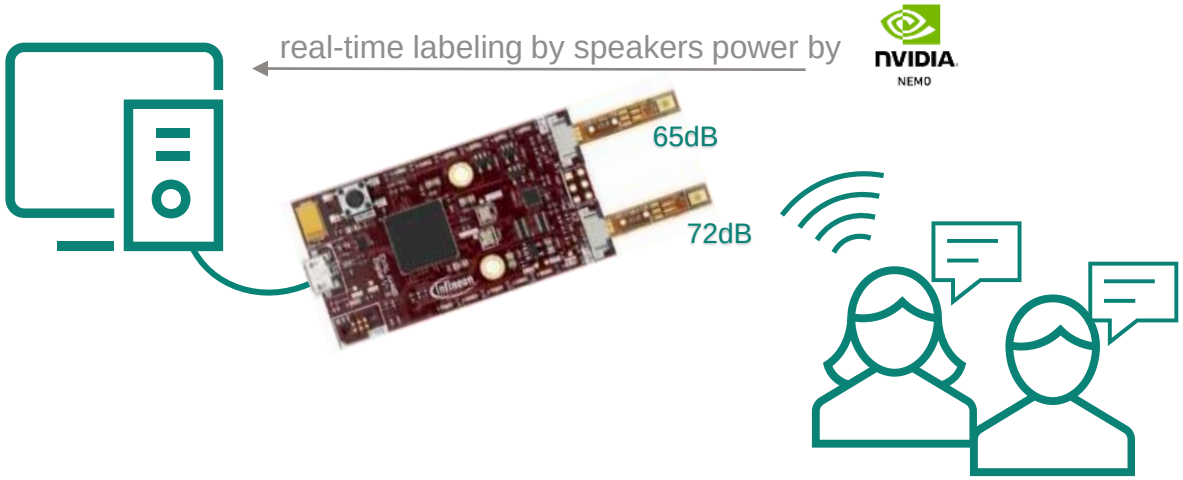
To understand the importance of high SNR microphones for speaker diarization, we conducted a study using two different microphones

The challenge:
Classify multiple speakers in different environments



The setup:
65 dB and 72 dB SNR microphones capturing the same scenario



The future:

- Automated, accurate transcripts with clear separation of speakers
- Voice control inputs from multiple speakers

Different scenarios:

- 2 person conversations female/female & female/male
  - No background noise
  - Low background noise e.g. television in the background
  - Higher background noise people chatting close by

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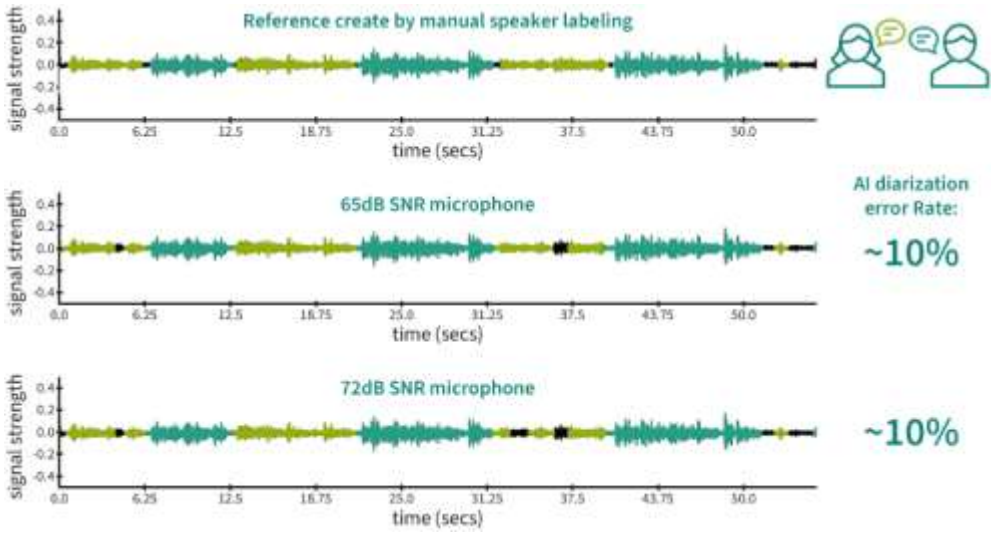
Our study reveals that high SNR microphones significantly improve the diarization quality in noisy environments

In quiet / low background noise environment

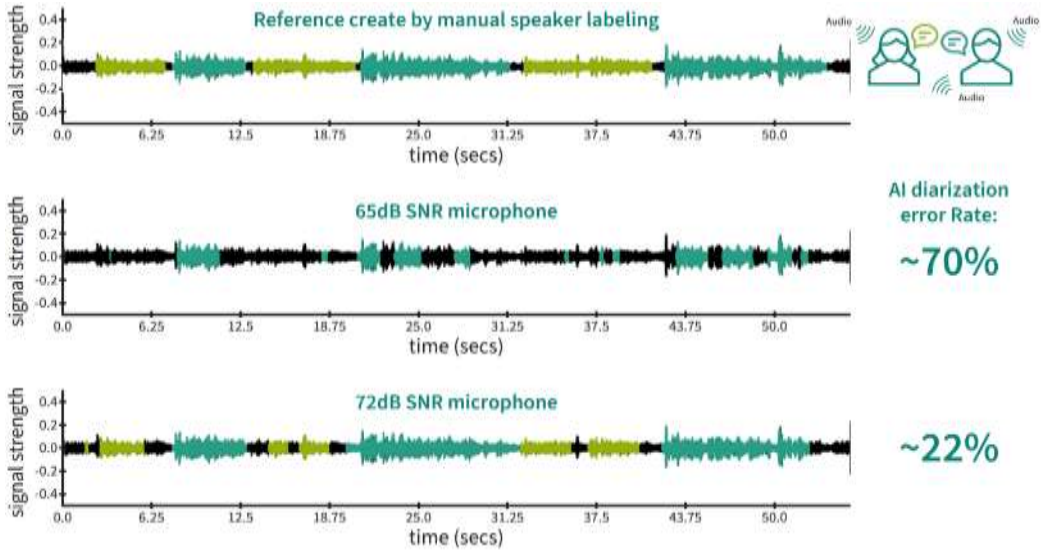
Result → Negligible Difference between 65dB and 72dB



65dB SNR Mic Diarization Error Rate	0.100	→ 10%
72dB SNR Mic Diarization Error Rate	0.113	→ 11.3%

In noisy background environment

Result → 72dB shows lower Diarization Error Rate



65dB SNR Mic Diarization Error Rate	0.709	→ 70.9%
72dB SNR Mic Diarization Error Rate	0.219	→ 21.9%

DER (Diarization Error Rate) High SNR microphone outperforms 65dB in noisy environment

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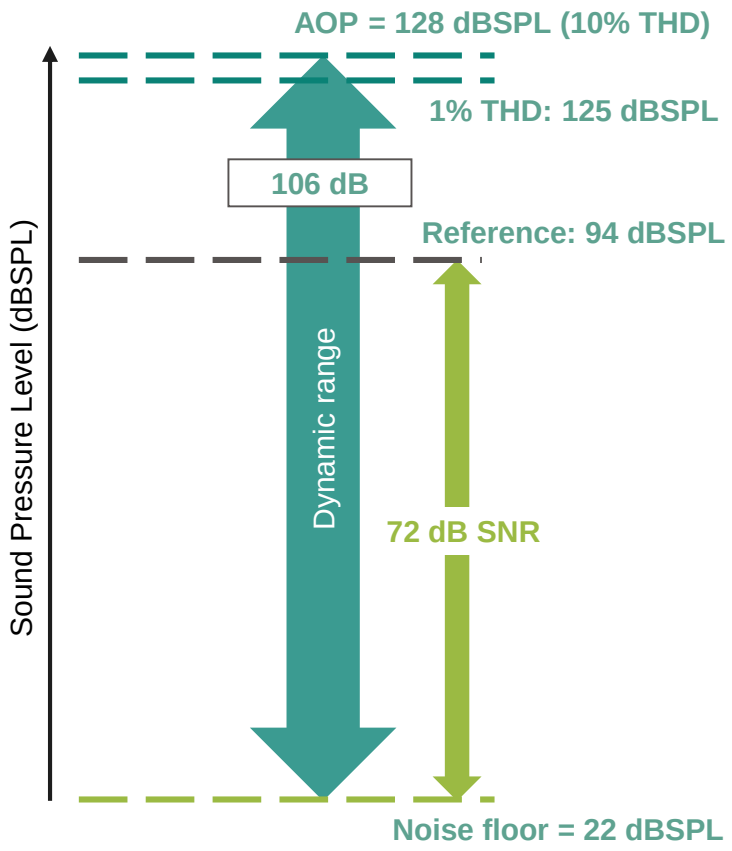
Infineon XENSIV™ MEMS microphone portfolio and roadmap

Overview of core microphone parameters and Infineon's naming convention

Microphone parameters



SNR: Signal to Noise ratio
Referenced to 94 dBSPL; indicates the noise floor level → "quietest sounds that can be captured"

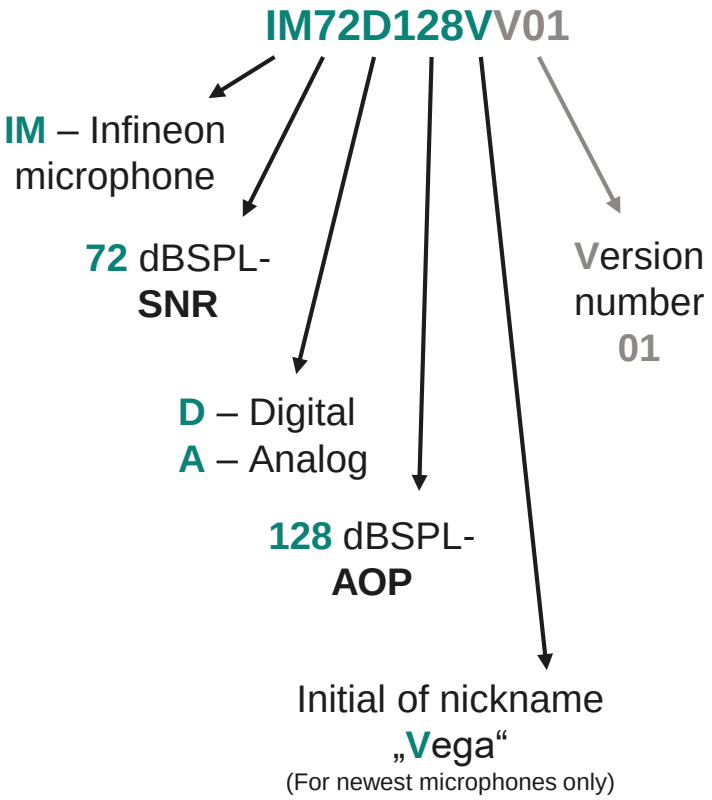
AOP: Acoustic Overload Point
Upper sound pressure level (SPL) limit beyond which the sound is heavily distorted; 10% total harmonic distortion (THD) → "loudest sounds that can be recorded without distortion"

SEN: Sensitivity
Ratio of the analog output voltage or digital output value to the sound pressure level of the incoming sound wave

IDD: Current consumption

CF: Corner frequency / Low frequency roll off point (LFRO)

Infineon microphone naming



Example: **IM72D128V**V01 XENSIV™ MEMS microphone with **Ultra high SNR & low IDD**

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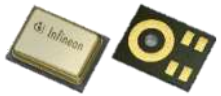
Analog SE / Differential
XENSIV™ MEMS microphone portfolio

Single backplate

Sealed dual membrane (IP57)

Analog SE

IM68A130 “Akari”



Low CF in small package

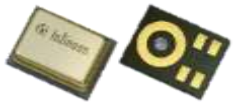
3.35 mm x 2.5 mm x 1.0 mm

SEN	-38 dBV
AOP	130 dBSPL
SNR	68 dB(A)
IDD	110 µA
CF	10 Hz



Analog Differential

IM70A135 “Alex”



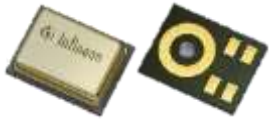
High SNR & very high AOP in small package

3.5 mm x 2.65 mm x 0.98 mm

SEN	-38 dBV
AOP	135 dBSPL
SNR	70 dB(A)
IDD	170/70 µA
CF	37 Hz



IM73A135 “Gustav”



Ultra high SNR & very high AOP

4.0 mm x 3.0 mm x 1.2 mm

SEN	-38 dBV
AOP	135 dBSPL
SNR	73 dB(A)
IDD	170/70 µA
CF	20 Hz



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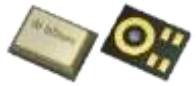
Digital PDM
XENSIV™ MEMS microphone portfolio

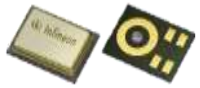
Single backplate
Dual backplate
Sealed dual membrane (IP57)

66-68dB SNR

IM68D128B “Bali”

3.5 x 2.65 x 0.98 mm
High SNR & low IDD

SEN	-37 dBFS
AOP	128 dBSPL
SNR	67.5 dB(A)
IDD	580/190 µA
CF	20 Hz

New!

IM66D132H “Hawaii”

3.5 x 2.65 x 0.98 mm
High 1%/10% THD & low IDD

SEN	-37 dBFS
AOP	132 dBSPL
SNR	66.5 dB(A)
IDD	580/190 µA
CF	20 Hz

New!

IM66D130M “Maui”

3 x 2 x 0.98 mm
Small package & low IDD

SEN	-37 dBFS
AOP	130 dBSPL
SNR	66 dB(A)
IDD	540/170 µA
CF	35 Hz

New!

IM67D128B “Bamboo”

3 x 2 x 0.98 mm
Small package & low IDD

SEN	-37 dBFS
AOP	128 dBSPL
SNR	67 dB(A)
IDD	540/170 µA
CF	10 Hz

New!

68 - 69dB SNR

IM69D120 “Charles”

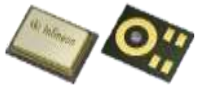
4.0 x 3.0 x1.2 mm
Legacy product

SEN	-26 dBFS
AOP	120 dBSPL
SNR	69 dB(A)
IDD	980/300 µA
CF	28 Hz

IM69D130 “Charles”

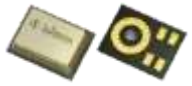
4.0 x 3.0 x 1.2 mm
Legacy product

SEN	-36 dBFS
AOP	130 dBSPL
SNR	69 dB(A)
IDD	980/300 µA
CF	28 Hz

IM68D121J “Java”

3.5 x 2.65 x 0.98 mm
High SNR, high sensitivity & low IDD

SEN	-26 dBFS
AOP	121 dBSPL
SNR	68 dB(A)
IDD	580/190 µA
CF	20 Hz

New!

IM69D128S “Squid”

3.5 x 2.65 x 0.98 mm
High SNR & low IDD

SEN	-37 dBFS
AOP	128 dBSPL
SNR	69 dB(A)
IDD	520/180µA
CF	30 Hz

IM69D129F “Fuji”

3.5 x 2.65 x 0.98 mm
High SNR, low IDD & low CF

SEN	-36 dBFS
AOP	129 dBSPL
SNR	69 dB(A)
IDD	450/140µA
CF	11 Hz

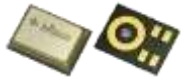
New!

IM69D127 “Apollo”

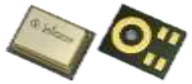
3.6 x 2.5 x 1.0 mm
High SNR

SEN	-34 dBFS
AOP	127 dBSPL
SNR	69 dB(A)
IDD	980/300µA
CF	40 Hz

70dB SNR

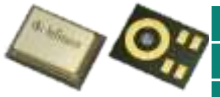
IM70D122 “Kassandra”

3.5 x 2.65 x 0.98 mm
Very high SNR & high Sensitivity

SEN	-26 dBFS
AOP	122 dBSPL
SNR	70 dB(A)
IDD	980/280 µA
CF	30 Hz

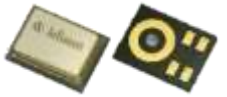
IM70D128T “Taurus”

3.5 x 2.65 x 0.98 mm
Very high SNR

SEN	-37 dBFS
AOP	128 dBSPL
SNR	70 dB(A)
IDD	980/280 µA
CF	30 Hz

≥72dB SNR

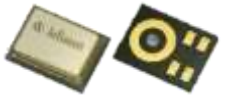
IM73D122 “Carl II”

4.0 x 3.0 x 1.2 mm
Ultra high SNR & high sensitivity

SEN	-26 dBFS
AOP	122 dBSPL
SNR	73 dB(A)
IDD	980/280 µA
CF	20 Hz

IM72D128V “Vega”

4.0 x 3.0 x 1.2 mm
Ultra high SNR & low IDD

SEN	-36 dBFS
AOP	128 dBSPL
SNR	71.5 dB(A)
IDD	430/120 µA
CF	11 Hz

New!

IM72D128 “Carl”

4.0 x 3.0 x 1.2 mm
Ultra high SNR

SEN	-36 dBFS
AOP	128 dBSPL
SNR	72 dB(A)
IDD	980/280 µA
CF	20 Hz

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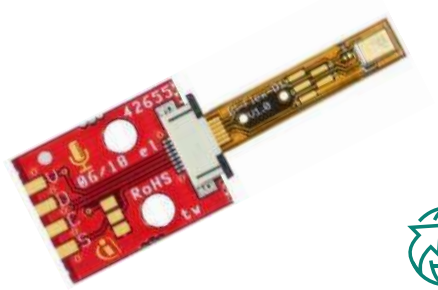
XENSIV™ MEMS microphone boards and online material

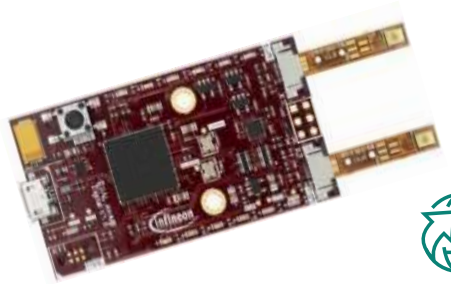
Infineon XENSIV™ MEMS microphone evaluation boards

Flex Kit



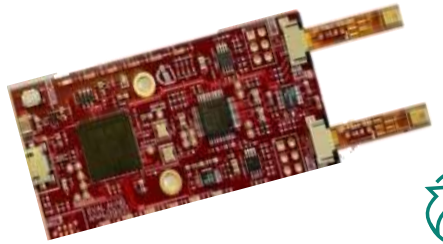
- Quick and easy connection to evaluation system
- Direct placement of flex board into a prototype
- PDM output
- Kit includes 5x flex boards and one adapter board

Audio Hub Nano Digital



- Audio Hub for digital PDM microphones
- Plug & play audio recordings
- Audio streaming over USB interface
- 24-bit, 48kHz stereo audio data

Audio Hub Nano Analog



- Audio Hub for Analog microphones
- Plug & play audio recordings
- Audio streaming over USB interface
- 24-bit, 48kHz stereo audio data

A²B Eval Kit



- Quick-start platform for software development to test different individual microphone configs
- System can be used for driving tests outside a demo car
- Up to 8 audio channels available
- Example SW-code available

Important links & support

Main page
Released datasheets, package information, application notes, and eval board information

Developer community
FAQs from developer community, comments from Infineon experts

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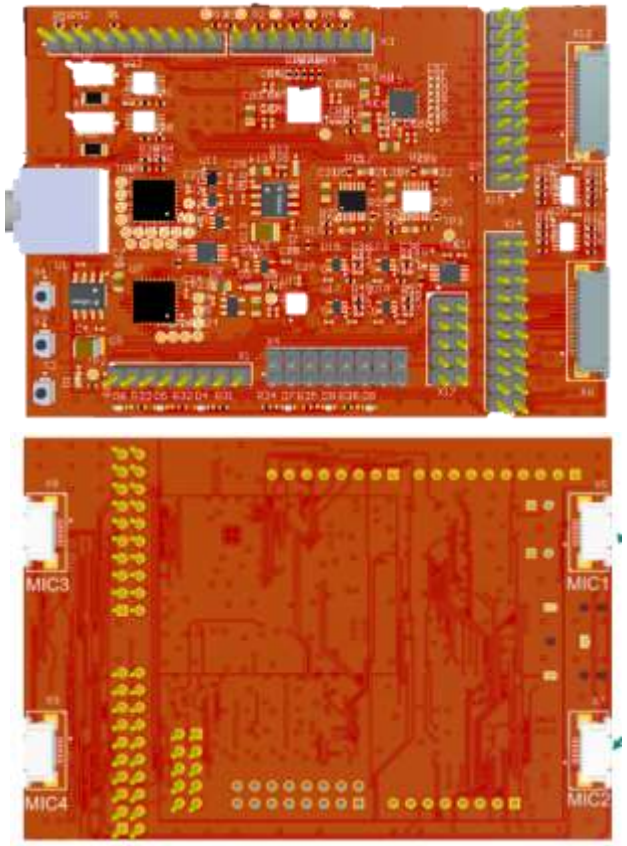
Available December 2025
Evaluating XENSIV™ MEMS microphone with PSoC6



XENSIV™ Audio Shield

- New microphone evaluation for XENSIV™ MEMS microphone
- Compatible with selected PSoC™6 Pioneer kits
  - PSOC™ 62S2 Evaluation Kit (CY8CEVAL-062S2)
  - PSOC™ 62S2 Wi-Fi Bluetooth® Pioneer Kit (CY8CKIT-062S2-43012)

- Compatible to all available XENSIV™ MEMS microphone flex kits
- Direct connection of 4 digital or 4 analog MEMS microphones via flex kits
- Possibility of interfacing up to 8 digital MEMS microphones
- Arduino interface, audio codec and headset jack

- Evaluation of microphone array applications
- Beamforming and advanced audio algorithm development
- Enabling ModusToolbox™ and Imagimob Studio for end-to-end software development and ML model development

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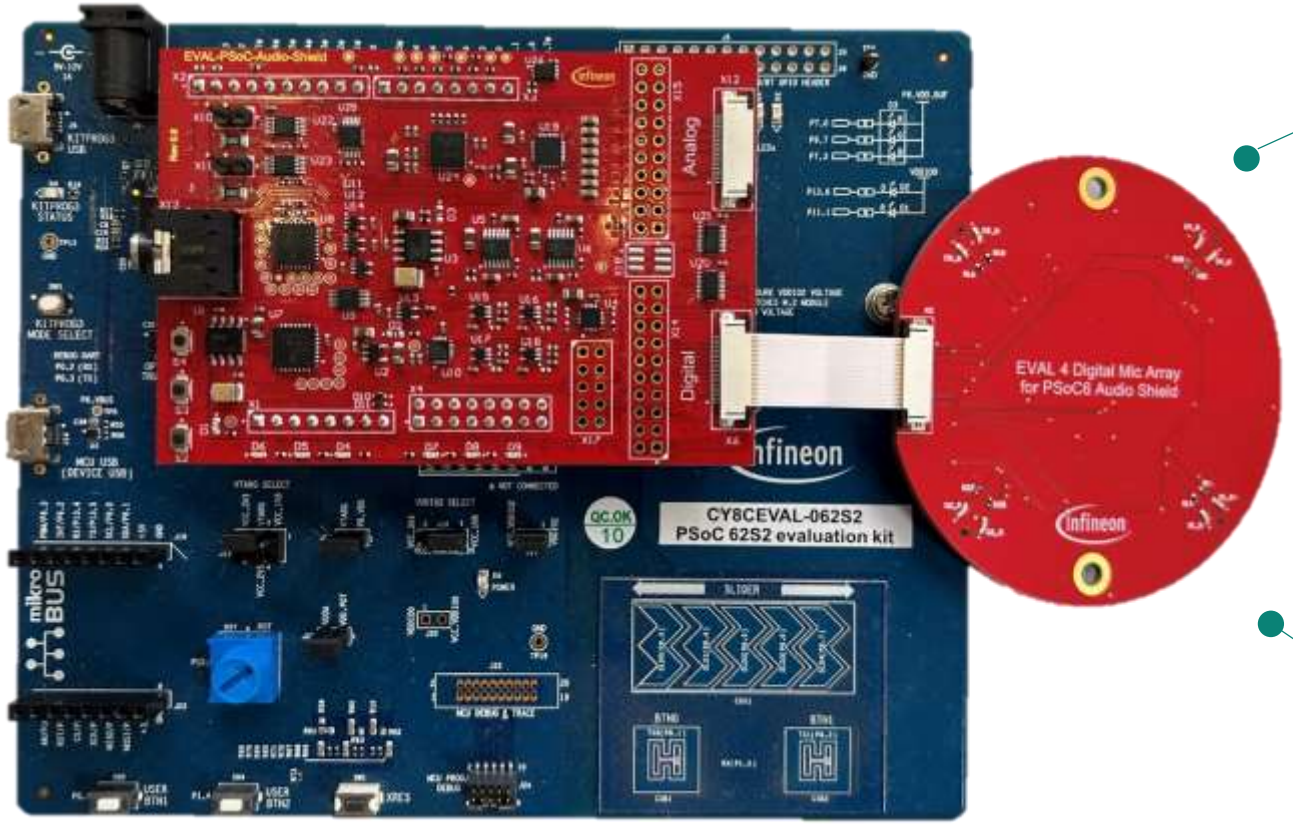
XENSIV™ Audio Shield Example Applications



Prototyping and development of stereo and multi-microphone solutions

Enabling advanced audio applications such as speech detection, beamforming, sound localization and environmental awareness

Evaluating and optimizing audio solutions end-to-end, for automotive, consumer and industrial applications

PSoC™ 6 MCU: XENSIV™ Microphone Audio Shield stereo
High performance stereo audio via full-speed USB using analog or digital XENSIV™ MEMS microphones

PSoC™ 6 MCU: XENSIV™ Microphone Audio Shield four-channels
High performance 4-ch audio via full-speed USB using analog or digital XENSIV™ MEMS microphones

more to come…

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PSoC™Edge AI MCU demo kit

Easy to use & low-cost

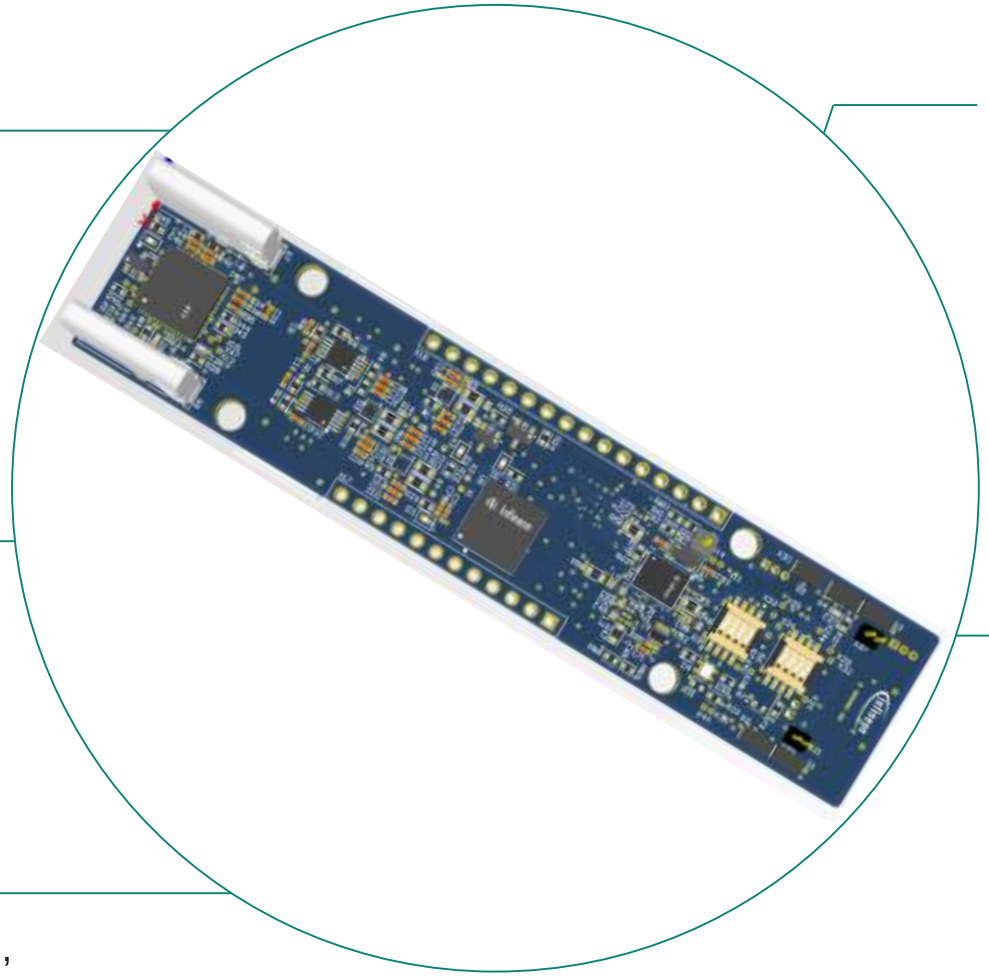
Evaluation board with efficient form factor for easy prototyping.
Cross compatible with the full Adafruit ecosystem.

Supporting all SURF sensors

Enabling sensor fusion-, ML-, acoustic-, time series- and radar models

End-to-end

Collect data, create, train, evaluate & deploy your ML models fast



Fast time to market at minimal development cost

Two direct PDM microphone flex connectors. Compatible with all digital XENSIV™ MEMS Microphone flex kits.

The best of Hardware, Software & ML

PSoC™Edge offers a high performing Cortex M55 MCU with up to 5 Mb RAM. Enabling edge solutions featuring complex algorithms.

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MEMS microphone applications

Smartphone

- Very high SNR for AI features
- High AOP for loud environments
- Small form factor

Hearables

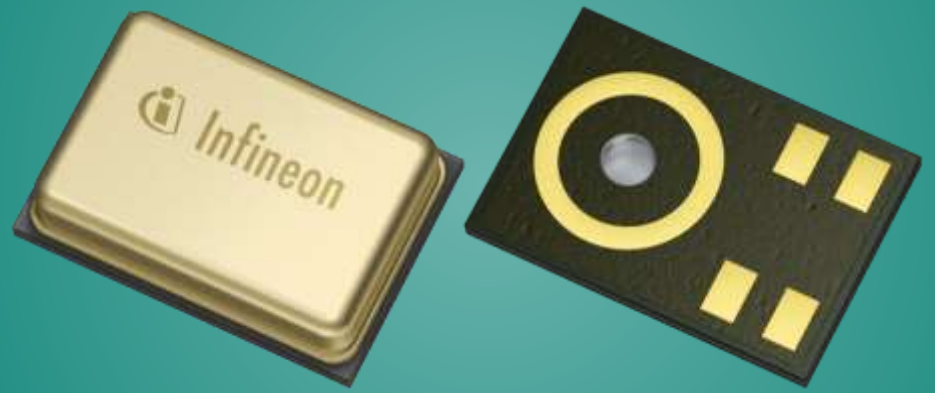
- Very high SNR for ANC
- Low latency for ANC
- Low power consumption
- Small - medium form factor
- Robustness against water / dust

Smart Glasses / AR

- High SNR for AI features
- Lowest power consumption
- Very small form factor

Notebook & Tablet

- High SNR for AI features
- Low latency for real-time calls
- Small form factor



Automotive

- High SNR for interior usage
- Robustness for exterior usage
- AEC-Q103 qualified

Smart Home & Office

- High SNR for far-field pickup
- Good phase / sensitivity matching

Smartwatch

- Robustness against water / dust
- Low power consumption
- Very small form factor

Camera

- High dynamic range
- Ultra-wide audio frequencies

Industrial

- Robustness against water / dust
- Tight part-to-part matching
- High AOP

Security Cameras

- Robustness against water / dust
- High SNR for far-field pickup
- Low power consumption

XENSIV™ microphones target mid to high-end consumer devices

Application	Use-cases	Microphone requirements	Recommendation
TWS earbuds 	– voice calling – transparent hearing – ANC	– Requires high and low end digital and analog microphones (SoC dependent) in small-medium form factor (up to 6 per set) and with low power consumption	**IM72D128V** **IM69D129F,** **IM68D128B**
Headphones 	– voice calling – transparent hearing – ANC	– Requires high and mid end digital and analog microphone (up to 10 per set)	**IM72D128V,** **IM73A135,** **IM69D128S**
Smartphone 	– voice assistance – far-field voice pickup – voice calling	– High robustness against ingress, mechanical stress and air blow required – Up to 3 mics in flagship models – Trend to high SNR driven by AI especially for flagship models	**IM70D128T** **IM66D132H** **IM66D130M**
Laptops & Tablets 	– conference calling – audio recording for content creation	– Trend towards higher audio performance for premium devices & home office applications – Requires high SNR for premium use-cases and small form-factor to fit in thin bezels	**IM73D122,** **IM70D122,** **IM68D121J**
Conference Systems & Home IoT 	– far-field voice pickup – conference calling	– Microphone array configurations utilize up to 32 high performance mics per system – Innovative beamforming and source separation capabilities-perfect match for XENSIV™	**IM73D122,** **IM70D122,** **IM68D121J**

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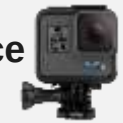
XENSIV™ microphones target mid to high-end consumer devices

Emerging	Use-cases	Microphone requirements	Recommendation
AR, VR , wearables 	– voice calling – voice control – audio recording	– Requires high and low end digital and analog microphones in a very small form factor and with lowest power consumption – Robustness and particle ingress protection	**IM69D128S, IM68D128B, IM66D130M**
Cameras, Surveillance 	– audio recording – far-field audio pick-up	– Requires good to high SNR and high acoustic overload point (AOP) and low power consumption for battery powered devices	**IM73D122, IM70D122, IM68D121J, IM73A135**
Content creation mics 	– high quality audio pick-up – background noise reduction	– Requires high to very high SNR and high acoustic overload point (AOP) and low power consumption for battery powered devices	**IM73A135, IM70A135**
Medical devices 	– vital sensing – sleep diagnostics – digital stethoscope	– Requires high SNR, high sensitivity and low power consumption for battery powered devices	**IM73A135, IM72D128V, IM68D128B**
Industrial applications < 	– predictive and preventive maintenance	– Very tight part-to-part phase and sensitivity matching (± 1dB) for multi-mic application – Flat frequency response with a very low LFRO (low frequency roll-off)	**IM72D128V IM73A135 IM69D128S IM68D128B**

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Trainings and support

New!

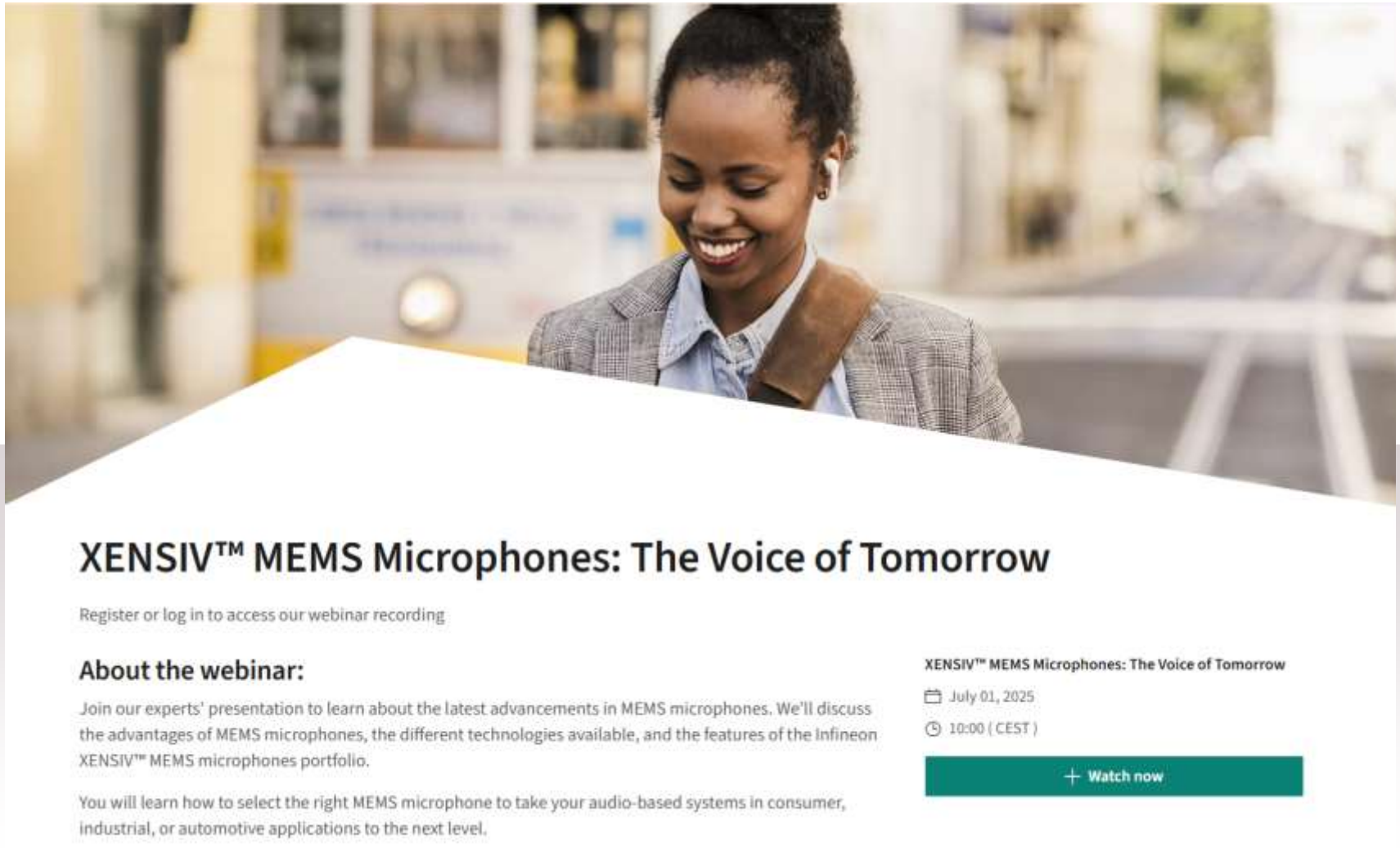
Find the latest MEMS microphone collaterals on myInfineon

myInfineon

- Product presentation
- Fighting guides
- App Notes
- Product Briefs & Data Sheets
- Whitepapers
- Articles
- Success Stories



Learn more about XENSIV™ MEMS microphones in our webinar recording “XENSIV™ MEMS Microphones: The Voice of Tomorrow”



https://www.infineon.com/event/webinar/2025/xensiv-mems-microphones-the-voice-of-tomorrow

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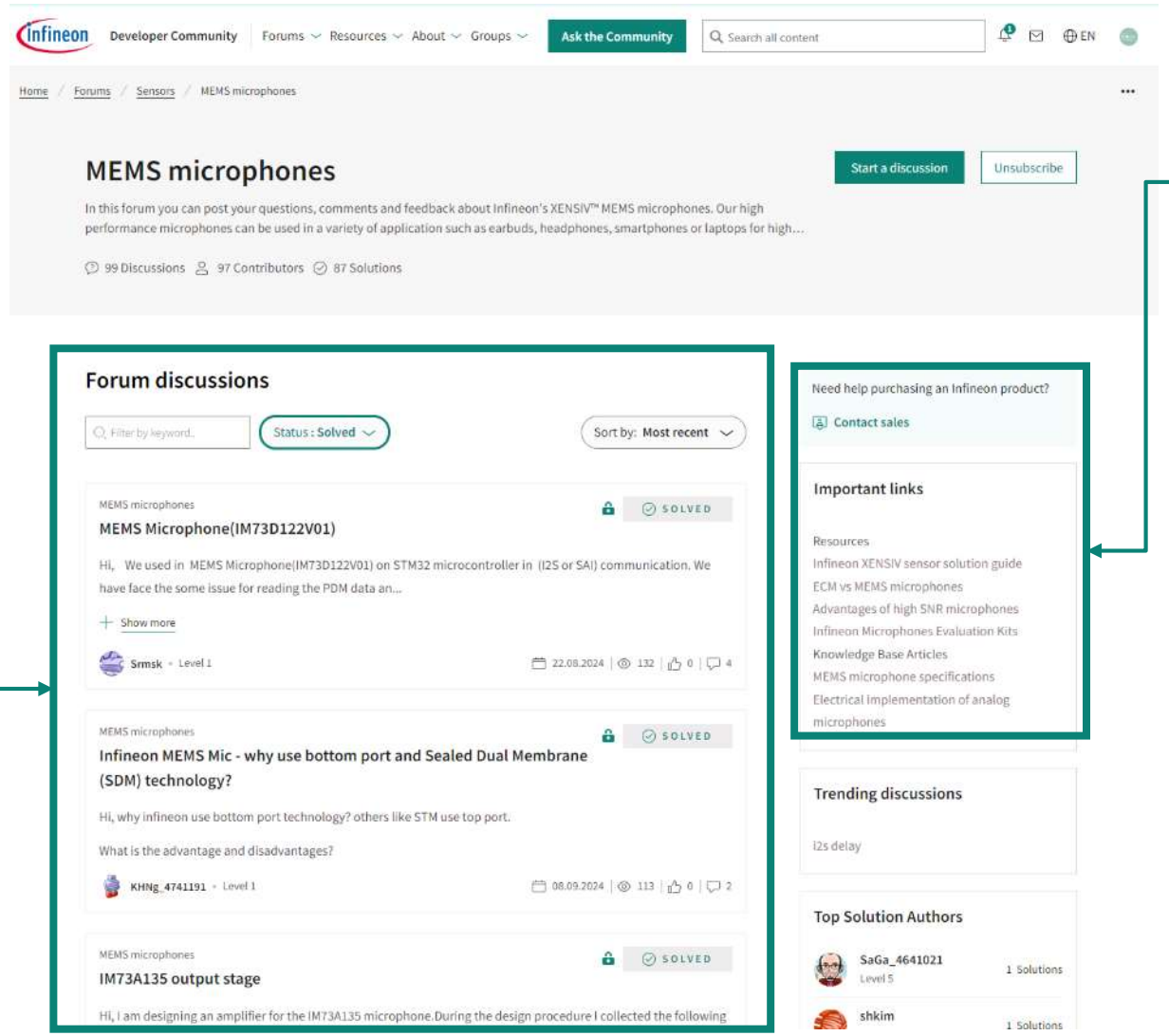
Discover our MEMS microphones *developer community*



Engage in a discussion

- ✓ Ask a question directly to our technical experts
- ✓ Learn from the peers and similar requests

Learn from our resources:

- ✓ Infineon XENSIV sensor solution guide
- ✓ ECM vs MEMS microphones
- ✓ Advantages of high SNR microphones
- ✓ Infineon Microphones Evaluation Kits
- ✓ MEMS microphone specifications
- ✓ Electrical implementation of analog microphones

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Support / Information



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